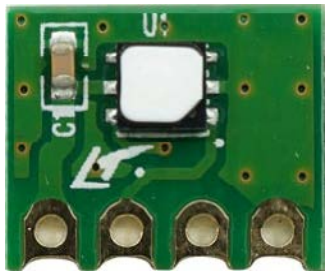
I²C HUMIDITY AND TEMPERATURE SENSOR

Features

- Precision Relative Humidity Sensor
  - ± 2.0% RH (Typ), 0–80% RH
- High Accuracy Temperature Sensor
  - ±0.3 °C (Typ), –10 to 85 °C
- 0 to 100% RH operating range
- –40 to +85 °C operating range
- Wide operating voltage (1.9 to 3.6 V)
- Low Power Consumption
  - 150 µA active current
  - 60 nA standby current
- Factory-calibrated
- I²C Interface
- Integrated on-chip heater
- 9.1mmx10.8 mm SMT Module
- Excellent long term stability
- Optional factory-installed cover
  - Low-profile
  - Protection during reflow
  - Excludes liquids and particulates



TH08: 9.1mmx10.8 mm SMT Module

Applications

- HVAC/R
- Thermostats/humidistats
- Respiratory therapy
- White goods
- Indoor weather stations
- Micro-environments/data centers
- Automotive climate control and defogging
- Asset and goods tracking
- Mobile phones and tablets

Description

The TH08 I2C Humidity and Temperature Sensor is a monolithic CMOS IC integrating humidity and temperature sensor elements, an analog-to-digital converter, signal processing, calibration data, and an I2C Interface. The patented use of industry-standard, low-K polymeric dielectrics for sensing humidity enables the construction of low-power, monolithic CMOS Sensor ICs with low drift and hysteresis, and excellent long term stability.
The humidity and temperature sensors are factory-calibrated and the calibration data is stored in the on-chip non-volatile memory. This ensures that the sensors are fully interchangeable, with no recalibration or software changes required
The TH08 is reflow solderable. It can be used as a hardware- and software-compatible drop-in upgrade for existing RH/ temperature sensors , featuring precision sensing over a wider range and lower power consumption. The optional factory-installed cover offers a low profile, convenient means of protecting the sensor during assembly (e.g., reflow soldering) and throughout the life of the product, excluding liquids (hydrophobic/oleophobic) and particulates. The TH08 offers an accurate, low-power, factory-calibrated digital solution ideal for measuring humidity, dew-point, and temperature, in applications ranging from HVAC/R and asset tracking to industrial and consumer platforms.

1. Electrical Specifications

Unless otherwise specified, all min/max specifications apply over the recommended operating conditions.

Table 1. Recommended Operating Conditions

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Power Supply	V_{DD}		1.9		3.6	V
Operating Temperature	T_A		–40	—	+125	°C

Table 2. General Specifications

1.9 ≤ V_{DD} ≤ 3.6 V; T_A = –40 to 125 °C default conversion time unless otherwise noted.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input Voltage High	V_{IH}	SCL, SDA pins	0.7xV_{DD}	—	—	V
Input Voltage Low	V_{IL}	SCL, SDA pins	—	—	0.3xV_{DD}	V
Input Voltage Range	V_{IN}	SCL, SDA pins with respect to GND	0.0	—	V_{DD}	V
Input Leakage	I_{IL}	SCL, SDA pins	—	—	1	µA
Output Voltage Low	V_{OL}	SDA pin; I_{OL} = 2.5 mA; V_{DD} = 3.3 V	—	—	0.6	V
		SDA pin; I_{OL} = 1.2 mA; V_{DD} = 1.9 V	—	—	0.4	V
Current Consumption	I_{DD}	RH conversion in progress	—	150	180	µA
		Temperature conversion in progress	—	90	120	µA
		Standby, –40 to +85 °C[2]	—	0.06	0.62	µA
		Standby, –40 to +125 °C[2]	—	0.06	3.8	µA
		Peak IDD during powerup[3]	—	3.5	4.0	mA
		Peak IDD during I^2C operations[4]	—	3.5	4.0	mA
		After writing to user registers[5]	—	20	—	µA
Heater Current[6]	I_{HEAT}		—	3.1	—	mA

Notes:

1. Initiating a RH measurement will also automatically initiate a temperature measurement. The total conversion time will be t_{CONV}(RH) + t_{CONV}(T).
2. No conversion or I^2C transaction in progress. Typical values measured at 25 °C.
3. Occurs once during powerup. Duration is <5 msec.
4. Occurs during I^2C commands for Reset, Read/Write User Registers, Read EID, and Read Firmware Version. Duration is <100 µs when I^2C clock speed is >100 kHz (>200 kHz for 2-byte commands).
5. IDD after a user register write. Initiating any other subsequent I^2C transaction on the same bus (such as the user register read, starting an RH measurement, or traffic directed at other I^2C devices) will transition the device to standby mode.
6. Additional current consumption when HTRE bit enabled. See section “5.5. Heater” for more information

Table 2. General Specifications (Continued)

1.9 ≤ V_{DD} ≤ 3.6 V; T_A = –40 to 125 °C default conversion time unless otherwise noted.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Conversion Time[1]	t_{CONV}	12-bit RH	—	10	12	ms
		11-bit RH	—	5.8	7	
		10-bit RH	—	3.7	4.5	
		8-bit RH	—	2.6	3.1	
		14-bit temperature	—	7	10.8	
		13-bit temperature	—	4	6.2	
		12-bit temperature	—	2.4	3.8	
		11-bit temperature	—	1.5	2.4	
Powerup Time	t_{PU}	From V_{DD} ≥ 1.9 V to ready for a conversion, 25 °C	—	18	25	ms
		From V_{DD} ≥ 1.9 V to ready for a conversion, full temperature range	—	—	80	
		After issuing a software reset command	—	5	15	

Notes:

1. Initiating a RH measurement will also automatically initiate a temperature measurement. The total conversion time will be t_{CONV}(RH) + t_{CONV}(T).
2. No conversion or I^2C transaction in progress. Typical values measured at 25 °C.
3. Occurs once during powerup. Duration is <5 msec.
4. Occurs during I^2C commands for Reset, Read/Write User Registers, Read EID, and Read Firmware Version. Duration is <100 µs when I^2C clock speed is >100 kHz (>200 kHz for 2-byte commands).
5. IDD after a user register write. Initiating any other subsequent I^2C transaction on the same bus (such as the user register read, starting an RH measurement, or traffic directed at other I^2C devices) will transition the device to standby mode.
6. Additional current consumption when HTRE bit enabled. See section “5.5. Heater” for more information

Table 3. I^2C Interface Specifications[1]

1.9 ≤ V_{DD} ≤ 3.6 V; T_A = –40 to +125 °C unless otherwise noted.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Hysteresis	V_{HYS}	High-to-low versus low-to-high transition	0.05 x V_{DD}	—	—	V
SCLK Frequency[2]	f_{SCL}		—	—	400	kHz
SCL High Time	t_{SKH}		0.6	—	—	µs
SCL Low Time	t_{SKL}		1.3	—	—	µs
Start Hold Time	t_{STH}		0.6	—	—	µs

Notes:

1. All values are referenced to V_{IL} and/or V_{IH}.
2. Depending on the conversion command, the TH08 may hold the master during the conversion (clock stretch). At above 100 kHz SCL, the TH08 may also hold the master briefly for user register and device ID transactions. At the highest I^2C speed of 400 kHz the stretching will be <10 µs.
3. Pulses up to and including 50 ns will be suppressed.

Table 3. I²C Interface Specifications[1] (Continued)

1.9 ≤ V_{DD} ≤ 3.6 V; T_A = –40 to +125 °C unless otherwise noted.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Start Setup Time	t_{STS}		0.6	—	—	µs
Stop Setup Time	t_{SPS}		0.6	—	—	µs
Bus Free Time	t_{BUF}	Between Stop and Start	1.3	—	—	µs
SDA Setup Time	t_{DS}		100	—	—	ns
SDA Hold Time	t_{DH}		100	—	—	ns
SDA Valid Time	$t_{VD;DAT}$	From SCL low to data valid	—	—	0.9	µs
SDA Acknowledge Valid Time	$t_{VD;ACK}$	From SCL low to data valid	—	—	0.9	µs
Suppressed Pulse Width[3]	t_{SPS}		50	—	—	ns

Notes:

1. All values are referenced to V_{IL} and/or V_{IH}.
2. Depending on the conversion command, the TH08 may hold the master during the conversion (clock stretch). At above 100 kHz SCL, the TH08 may also hold the master briefly for user register and device ID transactions. At the highest I²C speed of 400 kHz the stretching will be <10 µs.
3. Pulses up to and including 50 ns will be suppressed.

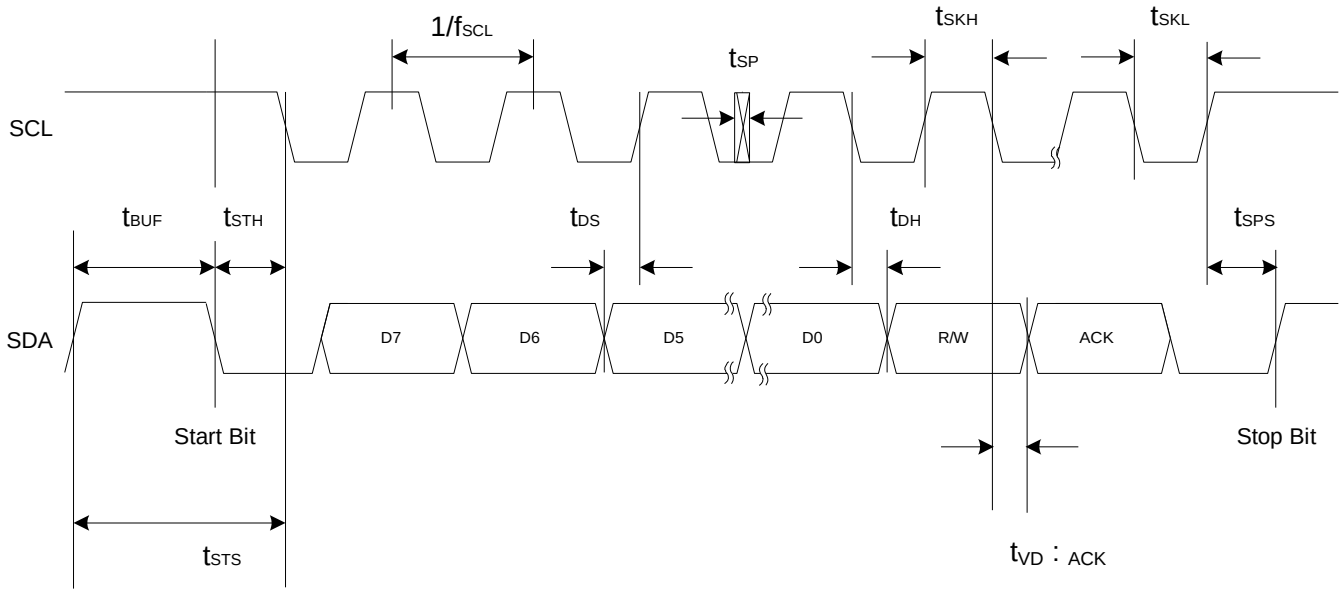


Figure 1. I²C Interface Timing Diagram

Table 4. Humidity Sensor

1.9 ≤ V_{DD} ≤ 3.6 V; T_A = 30 °C; default conversion time unless otherwise noted.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Operating Range[1]		Non-condensing	0	—	100	%RH
Accuracy[2, 3]		0 – 80% RH		±2.0		%RH
		80 – 100% RH	See Figure 2			
Repeatability/Noise		12-bit resolution	—	0.025	—	%RH RMS
		11-bit resolution	—	0.05	—	
		10-bit resolution	—	0.1	—	
		8-bit resolution	—	0.2	—	
Response Time[4]	$\tau_{63\%}$	1 m/s airflow	—	18	—	S
Drift vs. Temperature			—	0.05	—	%RH/°C
Hysteresis			—	±1	—	%RH
Long Term Stability[3]			—	≤ 0.25	—	%RH/yr

Notes:

1. Recommended humidity operating range is 20% to 80% RH (non-condensing) over –10 °C to 60 °C. Prolonged operation beyond these ranges may result in a shift of sensor reading, with slow recovery time.
2. Excludes hysteresis, long term drift, and certain other factors and is applicable to non-condensing environments only. See section “4.1. Relative Humidity Sensor Accuracy” for more details.
3. Drift due to aging effects at typical room conditions of 30 °C and 30% to 50% RH. May be impacted by dust, vaporized solvents or other contaminants, e.g., out-gassing tapes, adhesives, packaging materials, etc. See section “4.7. Long Term Drift/Aging” .
4. Response time to a step change in RH. Time for the RH output to change by 63% of the total RH change.

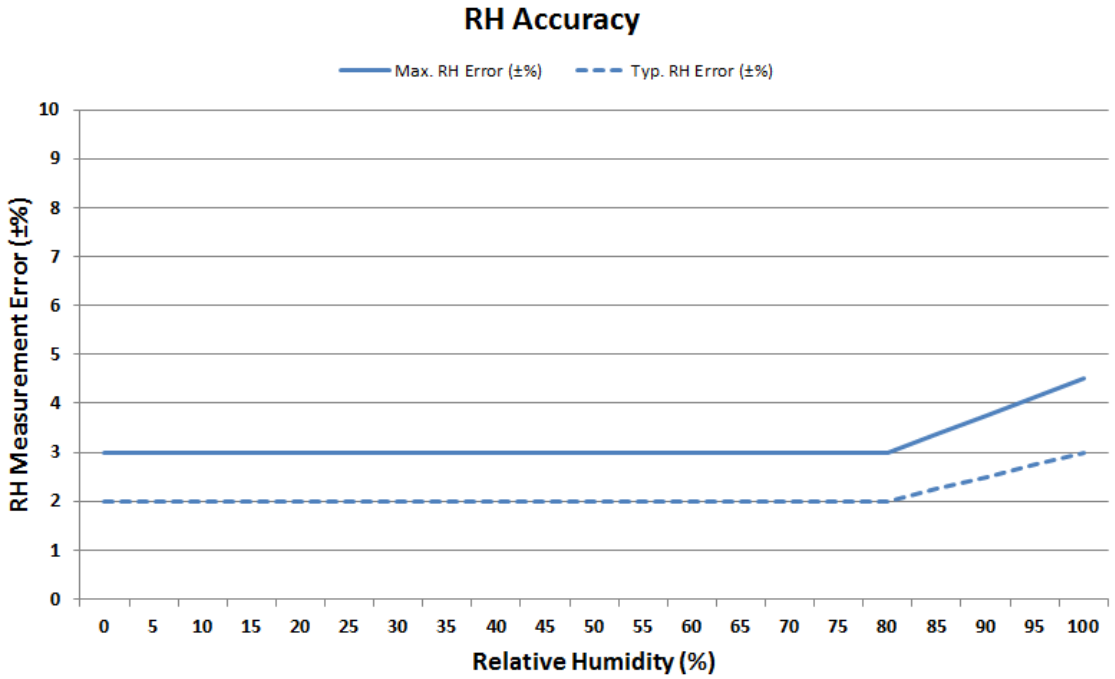


Figure 2. RH Accuracy at 30 °C

Table 5. Temperature Sensor

1.9 ≤ V_{DD} ≤ 3.6 V; T_A = –40 to +125 °C default conversion time unless otherwise noted.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Operating Range			–40	—	+125	°C
Accuracy[1]		–10 °C≤ t_A ≤ 85 °C	—	±0.5		°C
		–40 ≤ t_A ≤ 125 °C	Figure 3			
Repeatability/Noise		14-bit resolution	—	0.01	—	°C RMS
		13-bit resolution	—	0.02	—	
		12-bit resolution	—	0.04	—	
		11-bit resolution	—	0.08	—	
Response Time[2]	$\tau_{63\%}$	Unmounted device	—	0.7	—	s
		TH08 -EB board	—	5.1	—	s
Long Term Stability			—	≤ 0.01	—	°C/Yr

Notes:

1. 14b measurement resolution (default).
2. Time to reach 63% of final value in response to a step change in temperature. Actual response time will vary dependent on system thermal mass and air-flow.

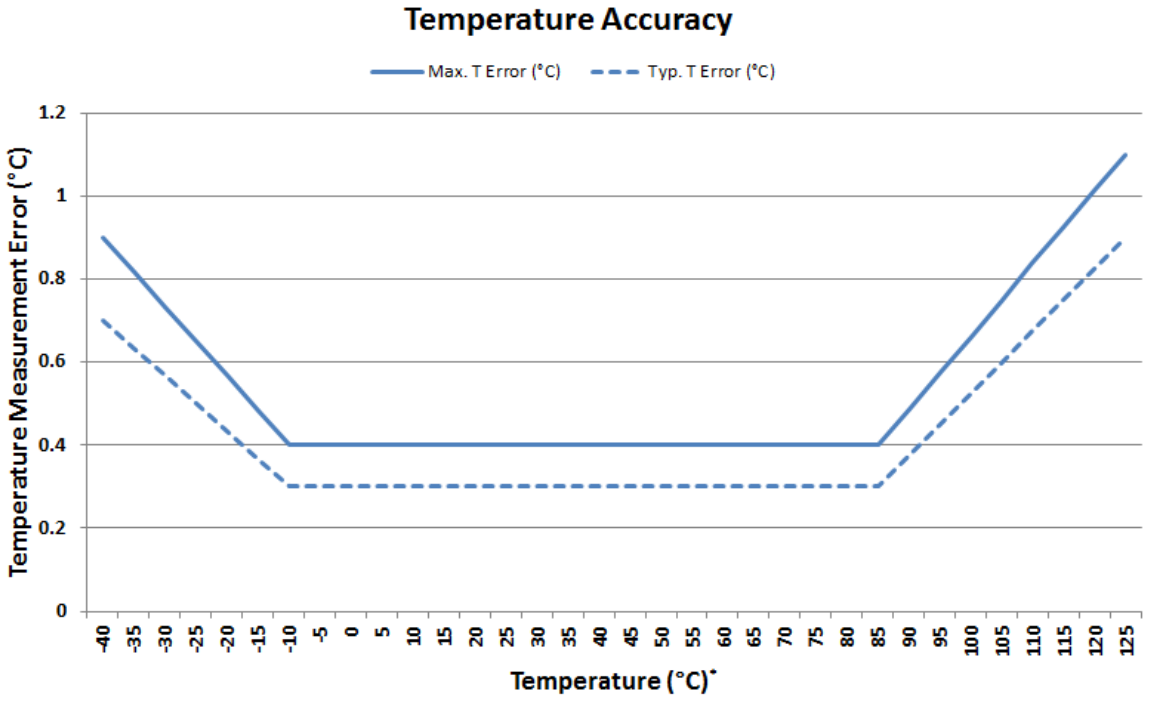


Figure 3. Temperature Accuracy

Table 6. Absolute Maximum Ratings[1]

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Ambient temperature under bias			–55	—	125	°C
Storage Temperature			–65	—	150	°C
Voltage on I/O pins			–0.3	—	VDD+0.3V	V
Voltage on VDD with respect to GND			–0.3		4.2	V
ESD Tolerance		HBM	—	—	2	kV
		CDM	—	—	1.25	kV
		MM	—	—	250	V

Notes:

1. Absolute maximum ratings are stress ratings only, operation at or beyond these conditions is not implied and may shorten the life of the device or alter its performance.

2. Typical Application Circuits

The primary function of the TH08 is to measure relative humidity and temperature. Figure 4 demonstrates the typical application circuit to achieve these functions.

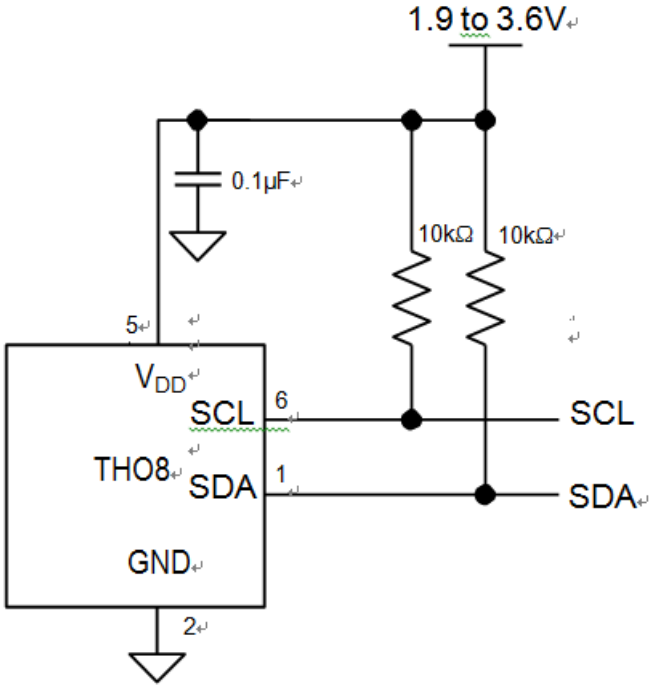


Figure 4. Typical Application Circuit for Relative Humidity and Temperature Measurement

3. Bill of Materials

Table 7. Typical Application Circuit BOM for Relative Humidity and Temperature Measurement

Reference	Description	Mfr Part Number	Manufacturer
R1	Resistor, 10 kΩ, ±5%, 1/16 W, 0603	CR0603-16W-103JT	Venkel
R2	Resistor, 10 kΩ, ±5%, 1/16 W, 0603	CR0603-16W-103JT	Venkel
C1	Capacitor, 0.1 µF, 16 V, X7R, 0603	C0603X7R160-104M	Venkel
U1	IC, Digital Temperature/humidity Sensor	TH08C	Hoperf

4. Functional Description

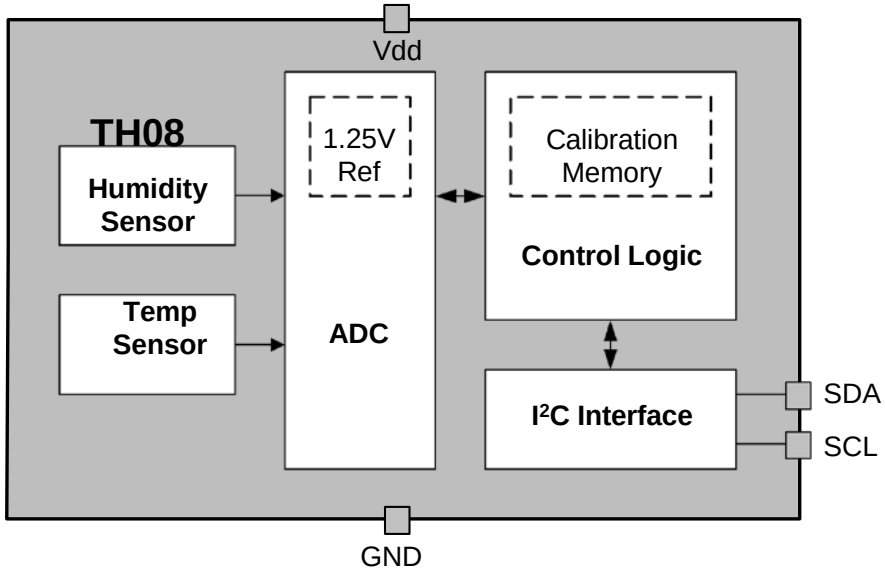


Figure 5. TH08 Block Diagram

The TH08 is a digital relative humidity and temperature sensor that integrates temperature and humidity sensor elements, an analog-to-digital converter, signal processing, calibration, polynomial non-linearity correction, and an I^2C interface all in a single chip. The TH08 is individually factory-calibrated for both temperature and humidity, with the calibration data stored in on-chip non-volatile memory. This ensures that the sensor is fully interchangeable, with no recalibration or changes to software required. Patented use of industry-standard CMOS and low-K dielectrics as a sensor enables the TH08 to achieve excellent long term stability and immunity to contaminants with low drift and hysteresis. The TH08 offers a low power, high accuracy, calibrated and stable solution ideal for a wide range of temperature, humidity, and dew-point applications including medical and instrumentation, high reliability automotive and industrial systems, and cost-sensitive consumer electronics.

While the TH08 is largely a conventional mixed-signal CMOS integrated circuit, relative humidity sensors in general and TH0se based on capacitive sensing using polymeric dielectrics have unique application and use requirements that are not common to conventional (non-sensor) ICs. Chief among TH0se are:

- The need to protect the sensor during board assembly, i.e., solder reflow, and the need to subsequently rehydrate the sensor.
- The need to protect the senor from damage or contamination during the product life-cycle.
- The impact of prolonged exposure to extremes of temperature and/or humidity and their potential effect on sensor accuracy.
- The effects of humidity sensor “memory”.

Each of these items is discussed in more detail in the following sections.

4.1. Relative Humidity Sensor Accuracy

To determine the accuracy of a relative humidity sensor, it is placed in a temperature and humidity controlled chamber. The temperature is set to a convenient fixed value (typically 25–30 °C) and the relative humidity is swept from 20 to 80% and back to 20% in the following steps: 20% – 40% – 60% – 80% – 80% – 60% – 40% – 20%. At each set-point, the chamber is allowed to settle for a period of 60 minutes before a reading is taken from the sensor. Prior to the sweep, the device is allowed to stabilize to 50%RH. The solid trace in Figure 6, “Measuring Sensor Accuracy Including Hysteresis,” shows the result of a typical sweep.

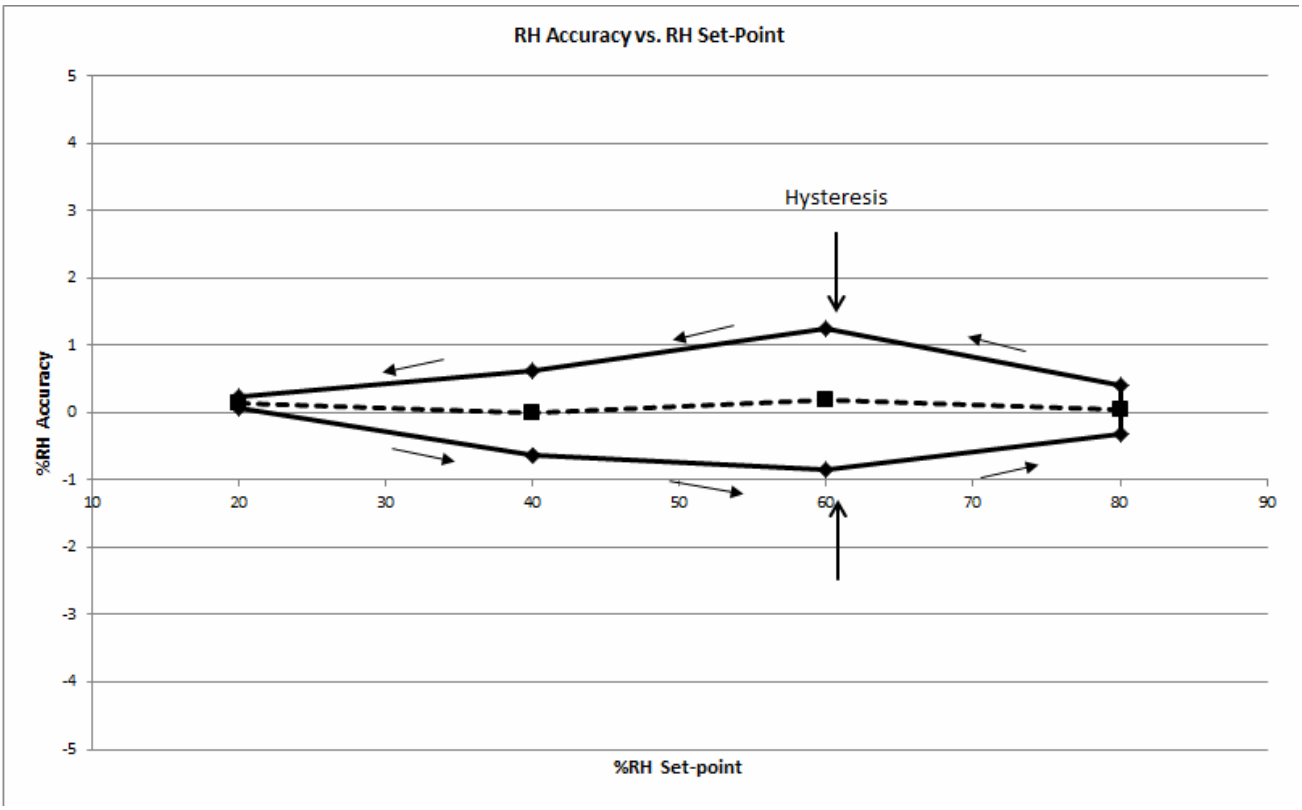


Figure 6. Measuring Sensor Accuracy Including Hysteresis

The RH accuracy is defined as the dotted line shown in Figure 6, which is the average of the two data points at each relative humidity set-point. In this case, the sensor shows an accuracy of 0.25%RH. The TH08 accuracy specification (Table 4) includes:

- Unit-to-unit and lot-to-lot variation
- Accuracy of factory calibration
- Margin for shifts that can occur during solder reflow

The accuracy specification does not include:

- Hysteresis (typically ±1%)
- Effects from long term exposure to very humid conditions
- Contamination of the sensor by particulates, chemicals, etc.
- Other aging related shifts ("Long-term stability")
- Variations due to temperature (see Drift vs. Temperature in Table 4). RH readings will typically vary with temperature by less than ± 0.05% ° C.

4.2. Hysteresis

The moisture absorbent film (polymeric dielectric) of the humidity sensor will carry a memory of its exposure history, particularly its recent or extreme exposure history. A sensor exposed to relatively low humidity will carry a negative offset relative to the factory calibration, and a sensor exposed to relatively high humidity will carry a positive offset relative to the factory calibration. This factor causes a hysteresis effect illustrated by the solid trace in Figure 6. The hysteresis value is the difference in %RH between the maximum absolute error on the decreasing humidity ramp and the maximum absolute error on the increasing humidity ramp at a single relative humidity setpoint and is expressed as a bipolar quantity relative to the average error (dashed trace). In the example of Figure 6, the measurement uncertainty due to the hysteresis effect is ±1.0%RH.

4.3. Prolonged Exposure to High Humidity

Prolonged exposure to high humidity will result in a gradual upward drift of the RH reading. The shift in sensor reading resulting from this drift will generally disappear slowly under normal ambient conditions. The amount of shift is proportional to the magnitude of relative humidity and the length of exposure. In the case of lengthy exposure to high humidity, some of the resulting shift may persist indefinitely under typical conditions. It is generally possible to substantially reverse this affect by baking the device (see section “4.6. Bake/Hydrate Procedure”).

4.4. PCB Assembly

4.4.1. Soldering

Like most ICs, TH08 devices are shipped from the factory vacuum-packed with an enclosed desiccant to avoid any RH accuracy drift during storage and to prevent any moisture-related issues during solder reflow. The following guidelines should be observed during PCB assembly:

- TH08 devices are compatible with standard board assembly processes. Devices should be soldered using reflow per the recommended card reflow profile. See Section “10. PCB Land Pattern and Solder Mask Design” for the recommended card reflow profile.
- A "no clean" solder process is recommended to minimize the need for water or solvent rinses after soldering. Cleaning after soldering is possible, but must be done carefully to avoid impacting the performance of the sensor.
- It is essential that the exposed polymer sensing film be kept clean and undamaged. This can be accomplished by careful handling and a clean, well-controlled assembly process. When in doubt or for extra protection, a heat-resistant, protective cover such as Kapton™ KPPD-1/8 polyimide tape can be installed during PCB assembly.

TH08 may be ordered with a factory-fitted, solder-resistant protective cover. This cover provides protection during PCB assembly or rework but wiTH0ut the time and effort required to install and remove the Kapton tape. It can be left in place for the lifetime of the product, preventing liquids, dust or other contaminants from coming into contact with the polymer sensor film. See Section “8. Ordering Guide” for a list of ordering part numbers that include the cover.

4.4.2. Rehydration

The measured humidity value will generally shift slightly after solder reflow. A portion of this shift is permanent and is accounted for in the accuracy specifications in Table 4. After soldering, an TH08 should be allowed to equilibrate under controlled RH conditions (room temperature, 45–55%RH) for at least 48 hours to eliminate the remainder of the shift and return the device to its specified accuracy performance.

4.5. Protecting the Sensor

Because the sensor operates on the principal of measuring a change in capacitance, any changes to the dielectric constant of the polymer film will be detected as a change in relative humidity. Therefore, it is important to minimize the probability of contaminants coming into contact with the sensor. Dust and other particles as well as liquids can affect the RH reading. It is recommended that a cover is employed in the end system that blocks contaminants but allows water vapor to pass through. Depending on the needs of the application, this can be as simple as plastic or metallic gauze for basic protection against particulates or something more sophisticated such as a hydrophobic membrane providing up to IP67 compliant protection.

The TH08 may be ordered with a factory-fitted, solder-resistant cover that can be left in place for the lifetime of the product. It is very low-profile, hydrophobic and oleophobic, and excludes particulates down to 0.35 microns in size. See section “8. Ordering Guide ” for a list of ordering part numbers that include the cover. A dimensioned drawing of the IC with the cover is included in section “9. Package Outline ” . Other characteristics of the cover are listed in Table8.

Table 8. Specifications of Protective Cover

Parameter	Value
Material	ePTFE
Water Entry Pressure	2.7 bar
Pore Size	0.35 µ
Operating Temperature	–40 to 125 °C
Maximum Reflow Temperature	260 °C
Oleophobicity (AATCC 118-1992)	7
IP Rating (per IEC 529)	IP67

4.6. Bake/Hydrate Procedure

After exposure to extremes of temperature and/or humidity for prolonged periods, the polymer sensor film can become either very dry or very wet, in each case the result is either high or low relative humidity readings. Under normal operating conditions, the induced error will diminish over time. From a very dry condition, such as after shipment and soldering, the error will diminish over a few days at typical controlled ambient conditions, e.g., 48 hours of 45 ≤ %RH ≤ 55. However, from a very wet condition, recovery may take significantly longer. To accelerate recovery from a wet condition, a bake and hydrate cycle can be implemented. This operation consists of the following steps:

- Baking the sensor at 125 °C for ≥ 12 hours
- Hydration at 30 °C in 75% RH for ≥ 10 hours

Following this cycle, the sensor will return to normal operation in typical ambient conditions after a few days.

4.7. Long Term Drift/Aging

Over long periods of time, the sensor readings may drift due to aging of the device. Standard accelerated life testing of the TH08 has resulted in the specifications for long-term drift shown in Table 4 and Table 5. This contribution to the overall sensor accuracy accounts only for the long-term aging of the device in an otherwise benign operating environment and does not include the effects of damage, contamination, or exposure to extreme environmental conditions.

5. I²C Interface

The TH08 communicates with the host controller over a digital I²C interface. The 7-bit base slave address is 0x40.

Table 9. I²C Slave Address Byte

A6	A5	A4	A3	A2	A1	A0	R/W
1	0	0	0	0	0	0	0

Master I²C devices communicate with the TH08 using a command structure. The commands are listed in the I²C command table10. Commands other than TH0se documented below are undefined and should not be sent to the device.

Table 10. I²C Command Table

Command Description	Command Code
Measure Relative Humidity, Hold Master Mode	0xE5
Measure Relative Humidity, No Hold Master Mode	0xF5
Measure Temperature, Hold Master Mode	0xE3
Measure Temperature, No Hold Master Mode	0xF3
Read Temperature Value from Previous RH Measurement	0xE0
Reset	0xFE
Write RH/T User Register 1	0xE6
Read RH/T User Register 1	0xE7

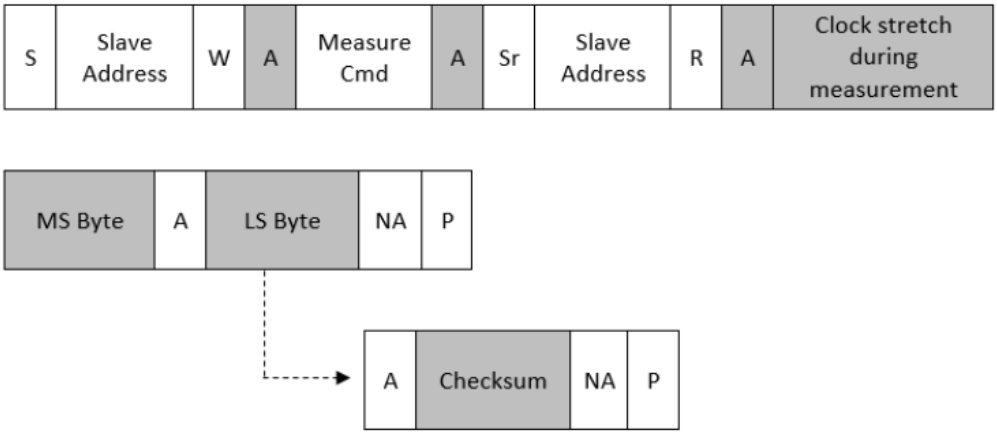
5.1. Issuing a Measurement Command

The measurement commands instruct the TH08 to perform one of two possible measurements; Relative Humidity or Temperature. The procedure to issue any one of these commands is identical. While the measurement is in progress, the option of either clock stretching (Hold Master Mode) or Not Acknowledging read requests (No Hold Master Mode) is available to indicate to the master that the measurement is in progress; the chosen command code determines which mode is used.

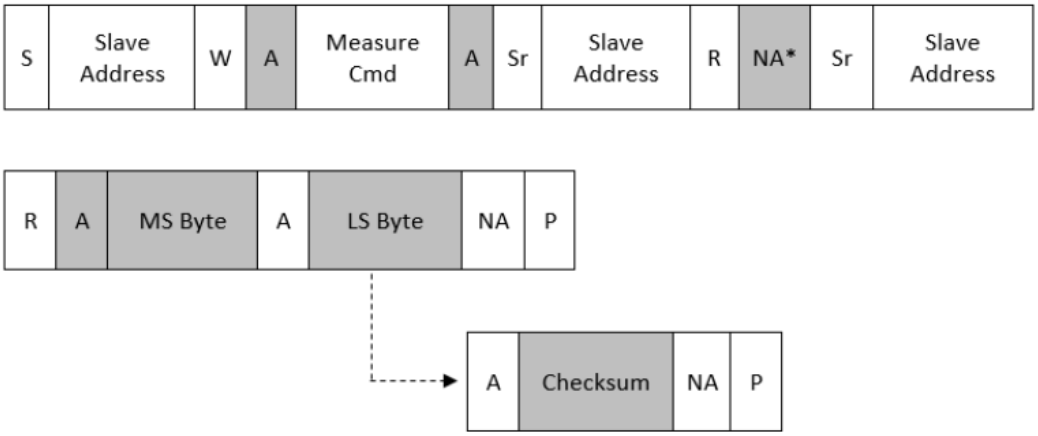
Optionally, a checksum byte can be returned from the slave for use in checking for transmission errors. The checksum byte will follow the least significant measurement byte if it is acknowledged by the master. The checksum byte is not returned if the master “not acknowledges” the least significant measurement byte. The checksum byte is calculated using a CRC generator polynomial of $x^8 + x^5 + x^4 + 1$, with an initialization of 0x00.

The checksum byte is optional after initiating an RH or temperature measurement with commands 0xE5, 0xF5, 0xE3, and 0xF3. For all other commands, the checksum byte is not supported.

Sequence to perform a measurement and read back result(Hold Master Mode)



Sequence to perform a measurement and read back result (No Hold Master Mode)



***Note: Device will NACK the slave address byte until conversion is complete**

5.1.1. Measuring Relative Humidity

Once a relative humidity measurement has been made, the results of the measurement may be converted to percent relative humidity by using the following expression:

$$\%RH = \frac{125*RH_Code}{65536} - 6$$

Where:

%RH is the measured relative humidity value in %RH

RH_Code is the 16-bit word returned by the TH08

A humidity measurement will always return XXXXXX10 in the LSB field.

Due to normal variations in RH accuracy of the device as described in Table 4, it is possible for the measured value of %RH to be slightly less than 0 when the actual RH level is close to or equal to 0. Similarly, the measured value of %RH may be slightly greater than 100 when the actual RH level is close to or equal to 100. This is expected behavior, and it is acceptable to limit the range of RH results to 0 to 100%RH in the host software by truncating values that are slightly outside of this range.

5.1.2. Measuring Temperature

Each time a relative humidity measurement is made a temperature measurement is also made for the purposes of temperature compensation of the relative humidity measurement. If the temperature value is required, it can be read using command 0xE0; this avoids having to perform a second temperature measurement. The measure temperature commands 0xE3 and 0xF3 will perform a temperature measurement and return the measurement value, command 0xE0 does not perform a measurement but returns the temperature value measured during the relative humidity measurement.

The checksum output is not available with the 0xE0 command.

Sequence to read temperature value from previous RH measurement

S	Slave Address	W	A	0xE0	A	Sr	Slave Address	R	A	MS Byte

A	LS Byte	NA	P

The results of the temperature measurement may be converted to temperature in degrees Celsius (°C) using the following expression:

$$\text{Temperature}(^{\circ}\text{C}) = \frac{175.72 * \text{Temp_Code}}{65536} - 46.85$$

Where:

Temperature (°C) is the measured temperature value in °C

Temp_Code is the 16-bit word returned by the TH08

A temperature measurement will always return XXXXXX00 in the LSB field.

5.2. Reading and Writing User Registers

There is one user register on the TH08 that allows the user to set the configuration of the TH08. The procedure for accessing that register is described below.

The checksum byte is not supported after reading a user register.

Sequence to read a register

S	Slave Address	W	A	Read Reg Cmd	A	Sr	Slave Address	R	A	Read Data	NA	P

Sequence to write a register

S	Slave Address	W	A	Write Reg Cmd	A	Write Data	A	P

5.3. Firmware Revision

The internal firmware revision can be read with the following I^2C transaction:

S	Slave Address	W	A	0x84	A	0xB8	A	S	Slave Address

R	A	FWREV	A	NA	P

The values in this field are encoded as follows:
0xFF=Firmware version 1.0

5.4. Heater

The TH08 contains an integrated resistive heating element that may be used to raise the temperature of the sensor. This element can be used to test the sensor, to drive off condensation, or to implement dew-point measurement when the TH08 is used in conjunction with a separate temperature sensor such as another TH08 (the heater will raise the temperature of the internal temperature sensor).

The heater can be activated using HTRE, bit 2 in User Register 1. Turning on the heater will reduce the tendency of the humidity sensor to accumulate an offset due to "memory" of sustained high humidity conditions.

6. Control Register

Table 11. Register Summary

Register	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
User Register 1	RES1	VDDS	RSVD	RSVD	RSVD	HTRE	RSVD	RES0

Notes:

1. Any register not listed here is reserved and must not be written. The result of a read operation on these bits is undefined.
2. Except where noted, reserved register bits will always read back as "1," and are not affected by write operations. For future compatibility, it is recommended that prior to a write operation, registers should be read. Then the values read from the RSVD bits should be written back unchanged during the write operation.

6.1. Register Descriptions

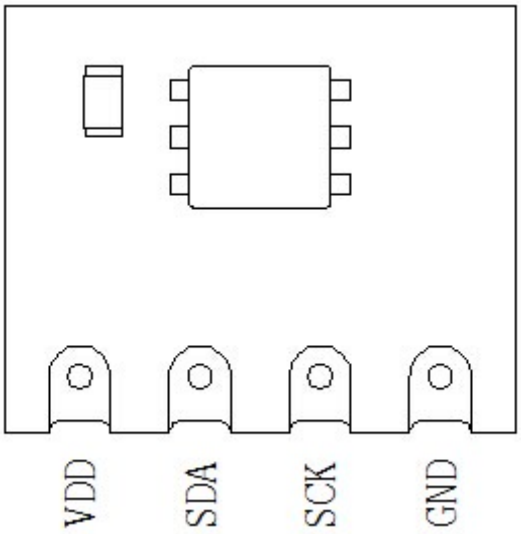
Register 1. User Register 1

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	RES1	VDDS	RSVD	RSVD	RSVD	HTRE	RSVD	RES0
Type	R/W	R	R/W	R/W		R/W	R/W	R/W

Reset Settings = 0011_1010

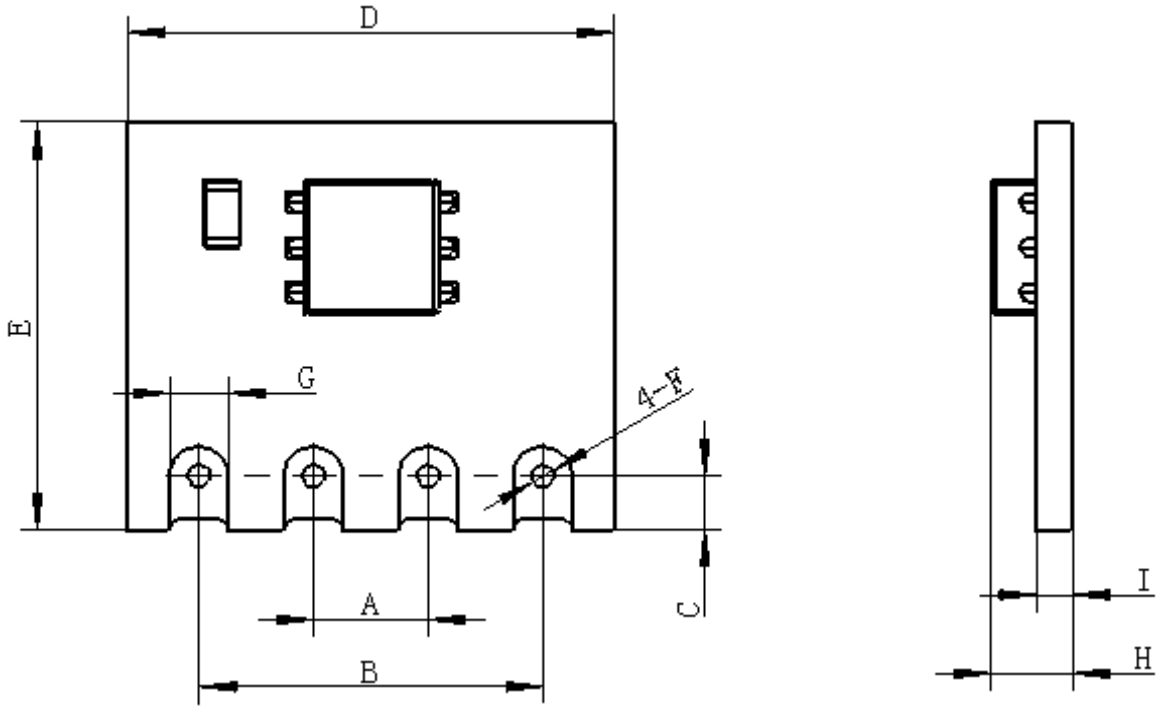
Bit	Name	Function
D7; D0	RES[1:0]	Measurement Resolution: RH / Temp 00: 12 bit / 14 bit 01: 8 bit / 12 bit 10: 10 bit / 13 bit 11: 11 bit / 11 bit
D6	VDDS	VDD Status: 0: V_{DD} OK 1: V_{DD} Low The minimum recommended operating voltage is 1.9 V. A transition of the VDD status bit from 0 to 1 indicates that VDD is between 1.8 V and 1.9 V. If the VDD drops below 1.8 V, the device will no longer operate correctly.
D5, D4, D3	RSVD	Reserved
D2	HTRE	1=On-chip Heater Enable 0=On-chip Heater Disable
D1	RSVD	Reserved

7. Pin Descriptions



Pin Name	Pin #	Pin Description
VDD	1	Power. This pin is connected to power on the circuit board.
SDA	2	I^2C data
SCL	3	I^2C clock
GND	4	Ground. This pin is connected to ground on the circuit board through a trace. Do not connect directly to GND plane.

8. Package Outline



Dimension	Min	Nom	Max
A	2.6	2.7	2.8
B	8.0	8.1	8.2
C	1.7	1.8	1.9
D		10.8	
E		9.1	
F	∮0.7	∮0..8	∮0.9
G	1.6	1.8	2.0
H	1.7	1.8	1.9
I	0.7	0.8	0.9

Notes:

1. All dimensions are shown in millimeters (mm).

HOPE MICROELECTRONICS CO.,LTD
Add: 2/F, Building 3, Pingshan Private Enterprise Science and Technology Park, Lishan Road, XiLi Town, Nanshan District, Shenzhen, Guangdong, China
Tel: 86-755-82973805
Fax: 86-755-82973550
Email: sales@hoperf.com
Website: http://www.hoperf.com
http://www.hoperf.cn

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